Abstracts

Investigation and Evaluation of Low Loss Interconnects on Soft Substrates Clad to Aluminum

T.M. Nelson and M.D. Kline. "Investigation and Evaluation of Low Loss Interconnects on Soft Substrates Clad to Aluminum." 1985 MTT-S International Microwave Symposium Digest 85.1 (1985 [MWSYM]): 188-191.

The purpose of this study is to provide a comparative evaluation of the quality of RF grounds used with microstrip circuitry on aluminum clad soft substrates. The data obtained by the study is documented and analyzed in the report with appropriate conclusions and recommendations provided.

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